

MTM23123

Silicon P-channel MOSFET

For switching

■ Overview

MTM23123 is P-channel MOS FET for load switch circuits.

■ Features

- Low voltage drive (2.5 V, 4 V)
- Realization of low on-resistance, using extremely fine process
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	-20	V
Gate-source surrender voltage	V_{GSS}	± 10	V
Drain current	I_D	-3.0	A
Peak drain current *1	I_{DP}	-16	A
Power dissipation *2	P_D	500	mW
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Pulse width $\leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

*2: Measuring on ceramic substrate at $40 \text{ mm} \times 38 \text{ mm} \times 0.1 \text{ mm}$

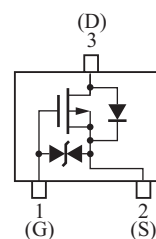
Absolute maximum rating without heat sink for P_D is 150 mW

■ Package

- Code
SMini3-G1-B
- Pin Name
1: Gate
2: Source
3: Drain

■ Marking Symbol: BL

■ Internal Connection



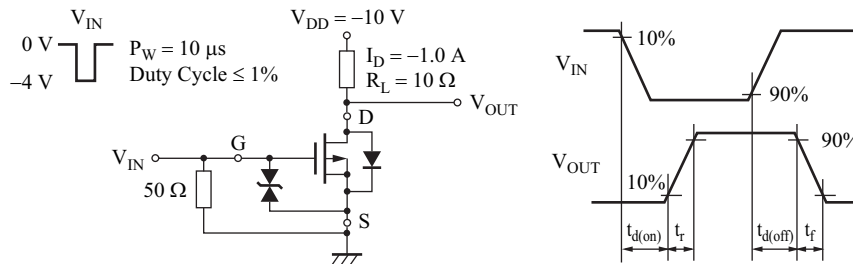
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

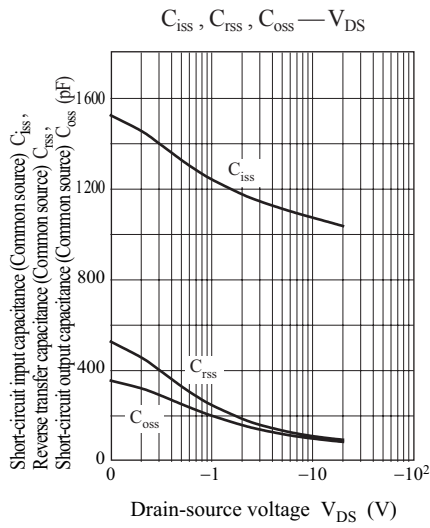
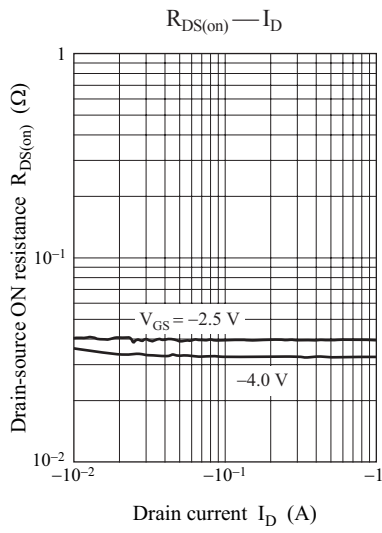
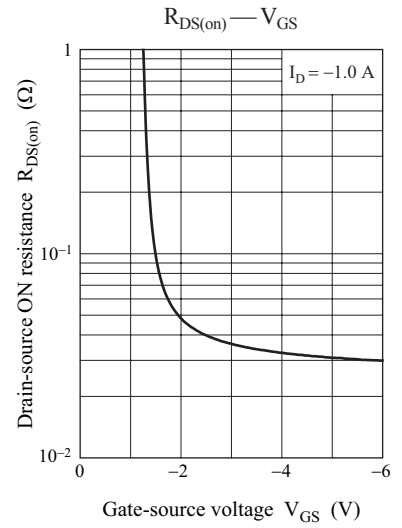
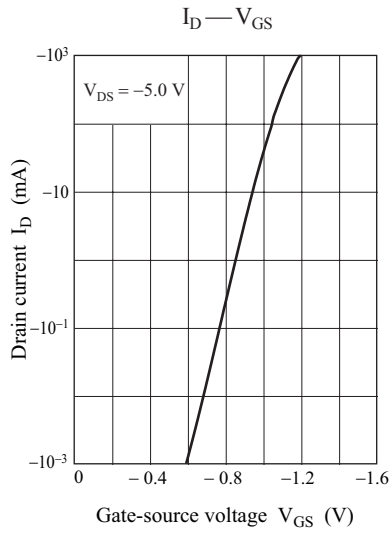
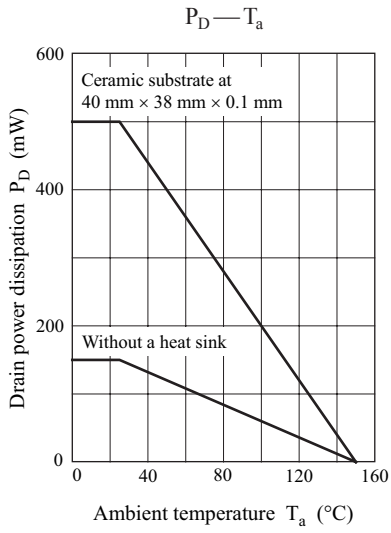
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source surrender voltage	V_{DSS}	$I_D = -1 \text{ mA}, V_{GS} = 0$	-20			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0$			-1.0	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$			± 10	μA
Gate threshold voltage	V_{TH}	$I_D = -1.0 \text{ mA}, V_{DS} = -10.0 \text{ V}$	-0.4	-0.85	-1.3	V
Drain-source ON resistance *1	$R_{DS(on)}$	$I_D = -1 \text{ A}, V_{GS} = -4.0 \text{ V}$		40	55	$\text{m}\Omega$
		$I_D = -0.5 \text{ A}, V_{GS} = -2.5 \text{ V}$		45	70	
Forward transfer admittance *1	$ Y_{fs} $	$I_D = -1.0 \text{ A}, V_{DS} = -10 \text{ V}, f = 1 \text{ kHz}$	3.5			S
Short-circuit input capacitance (Common source)	C_{iss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		1000		pF
Short-circuit output capacitance (Common source)	C_{oss}				120	pF
Reverse transfer capacitance (Common source)	C_{rss}				120	pF
Turn-on delay time *2	$t_{d(on)}$	$V_{DD} = -10 \text{ V}, V_{GS} = 0 \text{ V to } -4 \text{ V}, I_D = -1 \text{ A}$		25		ns
Rise time *2	t_r	$V_{DD} = -10 \text{ V}, V_{GS} = 0 \text{ V to } -4 \text{ V}, I_D = -1 \text{ A}$		25		ns
Turn-off delay time *2	$t_{d(off)}$	$V_{DD} = -10 \text{ V}, V_{GS} = -4 \text{ V to } 0 \text{ V}, I_D = -1 \text{ A}$		120		ns
Fall time *2	t_f	$V_{DD} = -10 \text{ V}, V_{GS} = -4 \text{ V to } 0 \text{ V}, I_D = -1 \text{ A}$		70		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement: Pulse width < 300 μs , Duty Cycle < 2.0%

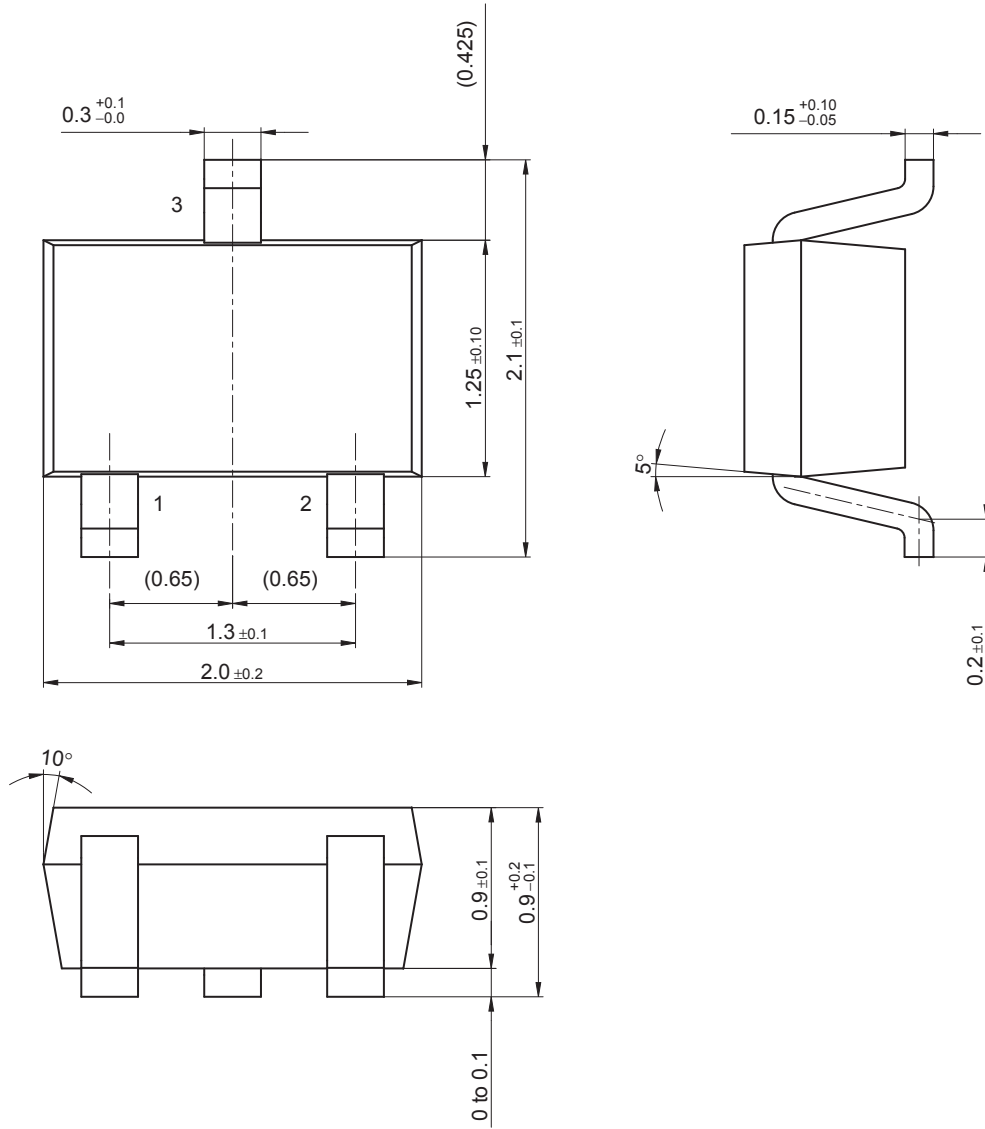
*2: Measurement circuit





SMini3-G1-B

Unit: mm



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